

C5729

Conductor

Description

C5729 is a gold conductor paste that has been formulated for use with Al or Au wire bond applications.

Key Features

- Excellent Al and Au bondability High conductivity Fine line printing



This picture does not show the packaging of C5729 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Conductivity	≤ 5.5 milliohms/square at 12 μm fired film thickness using 25 mil wide serpentine conductor pattern
Viscosity	380 – 480 Kcps, Brookfield HBTSC4 – 14 spindle and 6R utility cup at 10 rpm, 25 °C
Solids	86.5 ± 1.0 %
Coverage	118 cm ² /g at 12 μm fired film thickness (400 mesh, 0.9 mil wire, 0.5 mil emulsion)
Metal	AuAg

Recommended Processing Guide

Printing Parameters	280 mesh stainless steel screen 1.2 mil wire 45° angle 0.6 mil emulsion
Printing Speed	≥ 4 in/sec (≥ 10 cm/sec)
Drying Temperature	150 °C for 10 minutes Make sure ventilation is sufficient to prevent the wet film from skinning
Process Temperature (TDS)	850 °C peak temperature, 10 minutes at peak Total cycle time 45 – 60 minutes
Film Thickness	Dried: 20 – 22 μm Fired: 8 – 11 μm
Recommended Thinner	RV-372
Paste Compatibility	IP9217, IP9227 and IP9117D Multilayer Dielectrics

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Warranty

6 months

Storage

Store in a dry location at 5°C-25°C

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